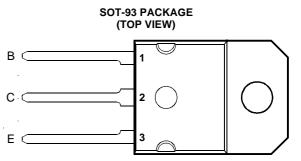
- Rugged Triple-Diffused Planar Construction
- 900 Volt Blocking Capability



Pin 2 is in electrical contact with the mounting base.

MDTRAA

#### absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
Collector base voltage $(I_{-} = 0)$	BU426	V	800	V
Collector-base voltage ( $I_E = 0$ )	BU426A	V <sub>CBO</sub>	900	v
Collector emitter veltere $(V = 0)$		V	800	V
Collector-emitter voltage ( $V_{BE} = 0$ )	BU426A	V <sub>CES</sub>	900	v
Collector-emitter voltage ( $I_B = 0$ )	BU426	V	375	V
	BU426A	V <sub>CEO</sub>	400	v
Continuous collector current	Ι <sub>C</sub>	6	A	
Peak collector current (see Note 1)	I <sub>CM</sub>	10	A	
Continuous base current	I <sub>B</sub>	+2, -0.1	A	
Peak base current (see Note 1)	I <sub>BM</sub>	±3	A	
Continuous device dissipation at (or below) 50°C case temperature	P <sub>tot</sub>	70	W	
Operating junction temperature range		Тj	-65 to +150	°C
Storage temperature range		T <sub>stg</sub>	-65 to +150	°C

NOTE 1: This value applies for  $t_p \le 2$  ms, duty cycle  $\le 2\%$ .



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#### electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
V <sub>CEO(sus)</sub>	Collector-emitter sustaining voltage	I <sub>C</sub> = 100 mA	L = 25 mH	(see Note 2)	BU426 BU426A	375 400			V
I <sub>CES</sub>	Collector-emitter cut-off current	$V_{CE} = 800 V$ $V_{CE} = 900 V$ $V_{CE} = 800 V$ $V_{CE} = 900 V$	$V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$	T <sub>C</sub> = 125°C T <sub>C</sub> = 125°C	BU426 BU426A BU426 BU426A			1 1 2 2	mA
I <sub>EBO</sub>	Emitter cut-off current	V <sub>EB</sub> = 10 V	$I_{\rm C} = 0$					10	mA
h <sub>FE</sub>	Forward current transfer ratio	V <sub>CE</sub> = 5 V	I <sub>C</sub> = 0.6 A	(see Notes 3 and 4)			30	60	
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	$I_{B} = 0.5 \text{ A}$ $I_{B} = 1.25 \text{ A}$	$I_{\rm C} = 2.5 \text{ A}$ $I_{\rm C} = 4 \text{ A}$	(see Notes 3 and 4)				1.5 3	V
V <sub>BE(sat)</sub>	Base-emitter saturation voltage	$I_{B} = 0.5 \text{ A}$ $I_{B} = 1.25 \text{ A}$	$I_{\rm C} = 2.5 \text{ A}$ $I_{\rm C} = 4 \text{ A}$	(see Notes 3 and 4)				1.4 1.6	V

NOTES: 2. Inductive loop switching measurement.

3. These parameters must be measured using pulse techniques, tp = 300  $\mu s,$  duty cycle  $\leq 2\%.$ 

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

### thermal characteristics

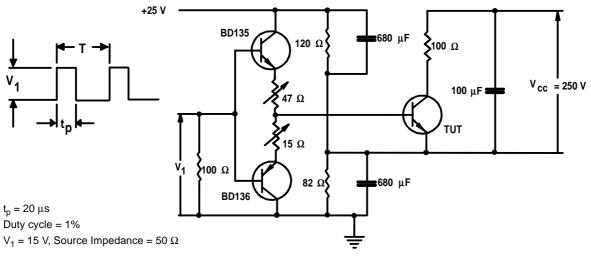
	PARAMETER			MAX	UNIT
R <sub>θJC</sub>	Junction to case thermal resistance			1.1	°C/W

#### resistive-load-switching characteristics at 25°C case temperature (unless otherwise noted)

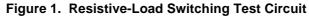
	PARAMETER	TEST CONDITIONS <sup>†</sup>			MIN	TYP	MAX	UNIT
t <sub>on</sub>	Turn on time	I <sub>C</sub> = 2.5 A		I		0.3	0.6	μs
t <sub>s</sub>	Storage time	$V_{\rm CC} = 250 {\rm V}$	I <sub>B(on)</sub> = 0.5 A (see Figures 1 and 2)	$I_{B(off)} = -1 A$		2	3.5	μs
t <sub>f</sub>	Fall time					0.15		μs
t <sub>f</sub>	Fall time	I <sub>C</sub> = 2.5 A V <sub>CC</sub> = 250 V	I <sub>B(on)</sub> = 0.5 A T <sub>C</sub> = 95°C	$I_{B(off)} = -1 A$		0.2	0.75	μs

<sup>†</sup> Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

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#### PARAMETER MEASUREMENT INFORMATION



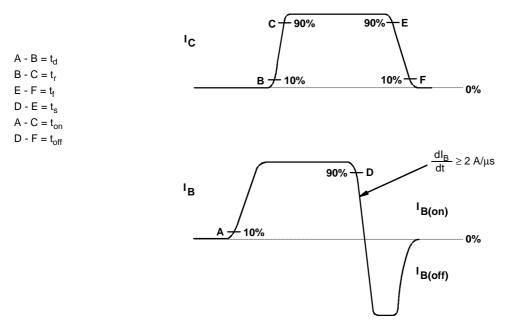
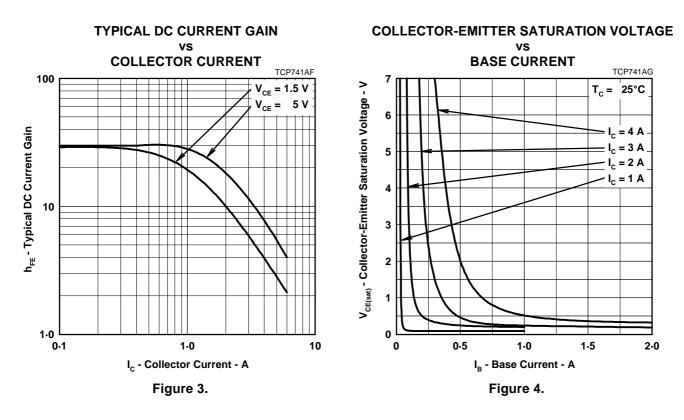


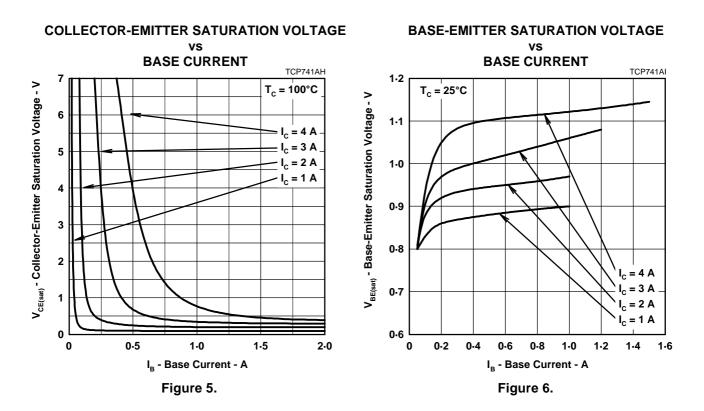
Figure 2. Resistive-Load Switching Waveforms



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#### **TYPICAL CHARACTERISTICS**



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#### MAXIMUM SAFE OPERATING REGIONS

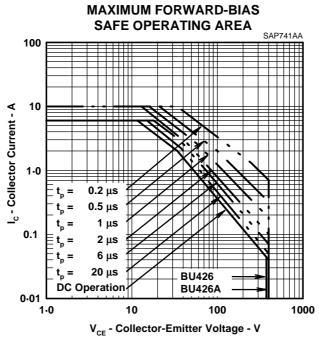


Figure 7.



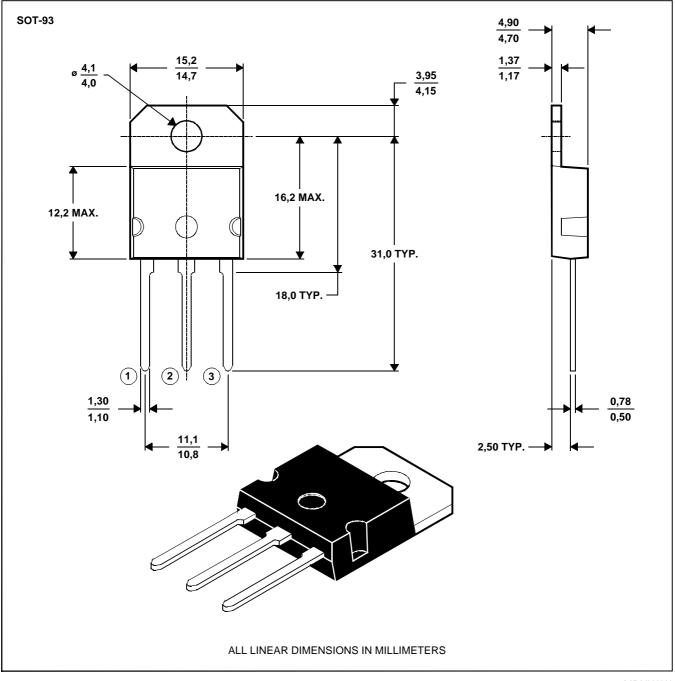
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### **MECHANICAL DATA**

### SOT-93

#### 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

MDXXAW

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